

ABSTRACT

The present invention relates to a resin composition containing (A) a thermosetting resin and (B) a copolymer resin containing a structural unit derived from an aromatic vinyl compound and a structural unit derived from an unsaturated aliphatic hydrocarbon, in which the component (B) contains a component (B1) having a content of a structural unit derived from an aromatic vinyl compound of 25 to 60% by mass, and a component (B2) having a content of a structural unit derived from an aromatic vinyl compound of less than that of the component (B1) on a mass basis, and the content of the component (B1) in the resin composition is greater than the content of the component (B2) in the resin composition on a mass basis; and a prepreg, a laminated board, a resin film, a printed wiring board, and a semiconductor package using the resin composition.